



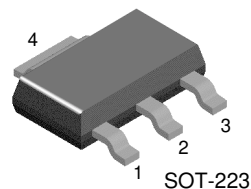
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BSP52

NPN Darlington Transistor

- This device is designed for applications requiring extremely high current gain at collector currents to 500mA.
- Sourced from process 03.



1. Base 2. Collector 3. Emitter

Absolute Maximum Ratings* $T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	80	V
V_{CBO}	Collector-Base Voltage	90	V
V_{EBO}	Emitter-Base Voltage	5	V
I_C	Collector Current - Continuous	800	mA
T_J, T_{STG}	Operating and Storage Junction Temperature Range	- 55 ~ +150	$^{\circ}\text{C}$

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- These ratings are based on a maximum junction temperature of 150°C .
- These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics $T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)CBO}$	Collector-Base Breakdown Voltage	$I_C = 100\mu\text{A}, I_E = 0$	90			V
$V_{(BR)EBO}$	Emitter-Base Breakdown Voltage	$I_E = 10\mu\text{A}, I_C = 0$	5			V
I_{CES}	Collector Cutoff Current	$V_{CE} = 80\text{V}, V_{BE} = 0$			10	μA
I_{EBO}	Emitter Cutoff Current	$V_{EB} = 4.0\text{V}, I_C = 0$			10	μA
On Characteristics						
h_{FE}	DC Current Gain	$I_C = 150\text{mA}, V_{CE} = 10\text{V}$ $I_C = 500\text{mA}, V_{CE} = 10\text{V}$	1000 2000			
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 500\text{mA}, I_B = 0.5\text{mA}$			1.3	V
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C = 500\text{mA}, I_B = 0.5\text{mA}$			1.9	V

Thermal Characteristics $T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Max.	Units
P_D	Total Device Dissipation Derate above 25°C	1000 8.0	mW mW/ $^{\circ}\text{C}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	$^{\circ}\text{C}/\text{W}$

Technical drawing of a mechanical part showing three views: front, side, and top. The front view shows a rectangular base with three vertical pins and a central raised section. The side view shows the profile of the base and pins. The top view shows the plan of the base. Dimensions are given in millimeters with tolerances.

Front View Dimensions:

- Top width: 3.00 ± 0.10
- Base width: 4.60 ± 0.25
- Pin width: 2.30 TYP
- Pin spacing: 0.70 ± 0.10
- Base height: 0.65 ± 0.20
- Pin height: 1.75 ± 0.20
- Pin diameter: $0.06^{+0.04}_{-0.02}$
- Pin length: 0.08 MAX
- Pin angle: $0^\circ \sim 10^\circ$

Side View Dimensions:

- Base width: 4.60 ± 0.25
- Pin width: 2.30 TYP
- Pin spacing: 0.70 ± 0.10
- Base height: 0.65 ± 0.20
- Pin height: 1.75 ± 0.20
- Pin diameter: $0.06^{+0.04}_{-0.02}$
- Pin length: 0.08 MAX
- Pin angle: $0^\circ \sim 10^\circ$

Top View Dimensions:

- Base width: 6.50 ± 0.20
- Pin width: 2.30 TYP
- Pin spacing: 0.70 ± 0.10
- Base height: 0.65 ± 0.20
- Pin height: 1.75 ± 0.20
- Pin diameter: $0.06^{+0.04}_{-0.02}$
- Pin length: 0.08 MAX
- Pin angle: $0^\circ \sim 10^\circ$

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